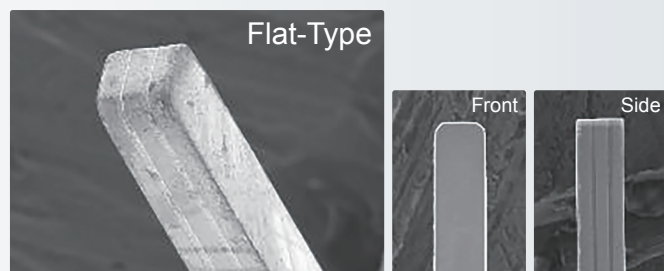
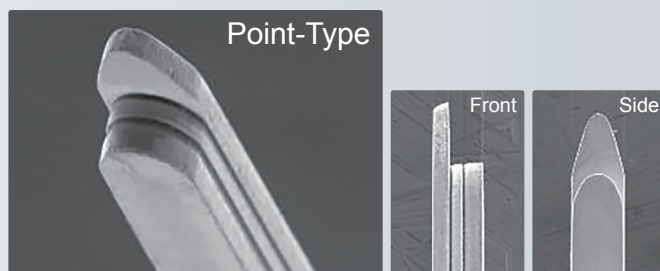


プリント基板&半導体パッケージ基板検査システム用
For printed circuit board and semiconductor package inspection system



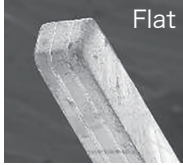
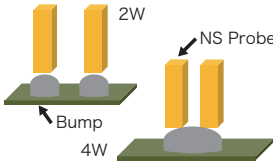
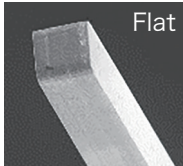
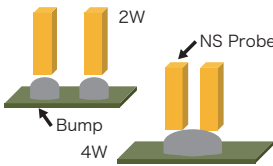
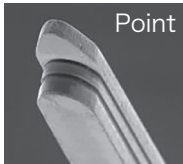
寸法精度の向上 | Good tolerance



材料選定が可能 | Select the body metal

MEMSプロセスを用いた微細化・先端形状の多様化を実現したプローブを開発
We developed the new probe that used MEMS process for min Pitch and possible to make various tip shape.

NS probe specifications

Probe Type	2W Pitch	4W Pitch	Tip Size	Force	Stroke	Raw Material	Contact Images
 Flat	55 μ m	Bump Pitch 100 μ m Probe Pitch 55 μ m	28×25 μ m	1.0gf	60 μ m	PdCo/Cu Isolation Coat Au Surface	
 Flat	45 μ m	Bump Pitch 80 μ m Probe Pitch 45 μ m	24×23 μ m	0.8gf	60 μ m	PdCo/Cu Isolation Coat Au Surface	
 Point	55 μ m	Bump Pitch 100 μ m Probe Pitch 35 μ m	28×25 μ m	1.0gf	60 μ m	PdCo/Cu Isolation Coat Au Surface	